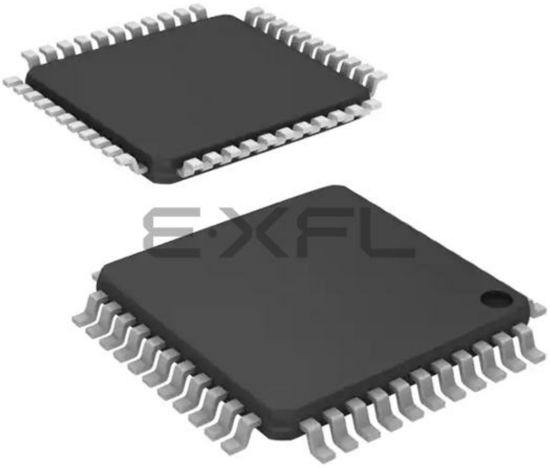


Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx220f032d-i-pt

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
OC1	PPS	PPS	PPS	PPS	O	—	Output Compare Output 1
OC2	PPS	PPS	PPS	PPS	O	—	Output Compare Output 2
OC3	PPS	PPS	PPS	PPS	O	—	Output Compare Output 3
OC4	PPS	PPS	PPS	PPS	O	—	Output Compare Output 4
OC5	PPS	PPS	PPS	PPS	O	—	Output Compare Output 5
OCFA	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault A Input
OCFB	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault B Input
INT0	13	16	17	43	I	ST	External Interrupt 0
INT1	PPS	PPS	PPS	PPS	I	ST	External Interrupt 1
INT2	PPS	PPS	PPS	PPS	I	ST	External Interrupt 2
INT3	PPS	PPS	PPS	PPS	I	ST	External Interrupt 3
INT4	PPS	PPS	PPS	PPS	I	ST	External Interrupt 4
RA0	27	2	33	19	I/O	ST	PORTA is a bidirectional I/O port
RA1	28	3	34	20	I/O	ST	
RA2	6	9	7	30	I/O	ST	
RA3	7	10	8	31	I/O	ST	
RA4	9	12	10	34	I/O	ST	
RA7	—	—	—	13	I/O	ST	
RA8	—	—	—	32	I/O	ST	
RA9	—	—	—	35	I/O	ST	
RA10	—	—	—	12	I/O	ST	
RB0	1	4	35	21	I/O	ST	PORTB is a bidirectional I/O port
RB1	2	5	36	22	I/O	ST	
RB2	3	6	1	23	I/O	ST	
RB3	4	7	2	24	I/O	ST	
RB4	8	11	9	33	I/O	ST	
RB5	11	14	15	41	I/O	ST	
RB6	12(2)	15(2)	16(2)	42(2)	I/O	ST	
RB7	13	16	17	43	I/O	ST	
RB8	14	17	18	44	I/O	ST	
RB9	15	18	19	1	I/O	ST	
RB10	18	21	24	8	I/O	ST	
RB11	19	22	25	9	I/O	ST	
RB12	20(2)	23(2)	26(2)	10(2)	I/O	ST	
RB13	21	24	27	11	I/O	ST	
RB14	22	25	28	14	I/O	ST	
RB15	23	26	29	15	I/O	ST	

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
PPS = Peripheral Pin Select
P = Power
I = Input
— = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.
2: Pin number for PIC32MX1XX devices only.
3: Pin number for PIC32MX2XX devices only.

3.2 Architecture Overview

The MIPS32 M4K processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32 M4K processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32 M4K processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown (‘32’ of 32x16) represents the *rs* operand. The second number (‘16’ of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

7.0 INTERRUPT CONTROLLER

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Interrupt Controller"** (DS60001108), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family devices generate interrupt requests in response to interrupt events from peripheral modules. The interrupt control module exists externally to the CPU logic and prioritizes the interrupt events before presenting them to the CPU.

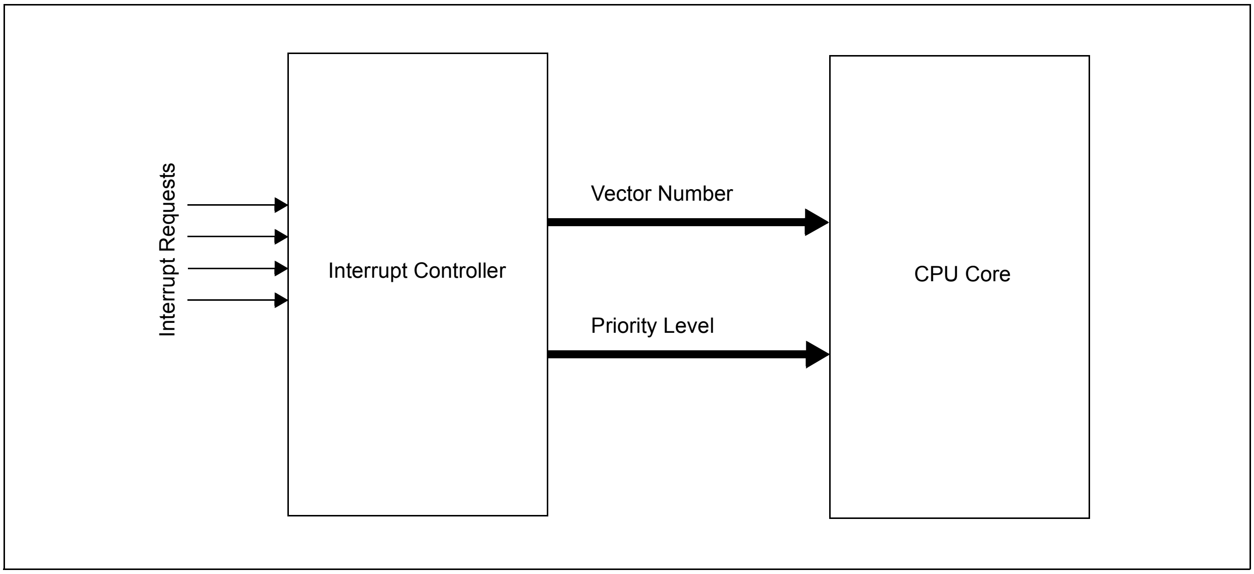
The PIC32MX1XX/2XX 28/36/44-pin Family interrupt module includes the following features:

- Up to 64 interrupt sources
- Up to 44 interrupt vectors
- Single and multi-vector mode operations
- Five external interrupts with edge polarity control
- Interrupt proximity timer
- Seven user-selectable priority levels for each vector
- Four user-selectable subpriority levels within each priority
- Software can generate any interrupt
- User-configurable Interrupt Vector Table (IVT) location
- User-configurable interrupt vector spacing

Note: The dedicated shadow register set is not present on PIC32MX1XX/2XX 28/36/44-pin Family devices.

A simplified block diagram of the Interrupt Controller module is illustrated in Figure 7-1.

FIGURE 7-1: INTERRUPT CONTROLLER MODULE BLOCK DIAGRAM



REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

bit 3-0	**ROSEL<3:0>:** Reference Clock Source Select bits[1] `1111` = Reserved; do not use • • • `1001` = Reserved; do not use `1000` = REFCLKI `0111` = System PLL output `0110` = USB PLL output `0101` = SOSC `0100` = LPRC `0011` = FRC `0010` = POSC `0001` = PBCLK `0000` = SYSCLK

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is ‘`1`’, as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = `0000` or `0001`.

3: While the ON bit is set to ‘`1`’, writes to these bits do not take effect until the DIVSWEN bit is also set to ’`1`’.

REGISTER 9-2: DMASTAT: DMA STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
	—	—	—	—	RDWR	DMACH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-4 **Unimplemented:** Read as ‘0’

bit 3 **RDWR:** Read/Write Status bit
1 = Last DMA bus access was a read
0 = Last DMA bus access was a write

bit 2-0 **DMACH<2:0>:** DMA Channel bits
These bits contain the value of the most recent active DMA channel.

REGISTER 9-3: DMAADDR: DMA ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<31:24>							
23:16	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<23:16>							
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-0 **DMAADDR<31:0>:** DMA Module Address bits
These bits contain the address of the most recent DMA access.

REGISTER 9-4: DCRCCON: DMA CRC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
	—	—	BYTO<1:0>		WBO[1]	—	—	BITO
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	PLEN<4:0>				
7:0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	CRCEN	CRCAPP[1]	CRCTYP	—	—	CRCCH<2:0>		

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Read as ‘0’

bit 29-28 **BYTO<1:0>:** CRC Byte Order Selection bits
11 = Endian byte swap on half-word boundaries (i.e., source half-word order with reverse source byte order per half-word)
10 = Swap half-words on word boundaries (i.e., reverse source half-word order with source byte order per half-word)
01 = Endian byte swap on word boundaries (i.e., reverse source byte order)
00 = No swapping (i.e., source byte order)

bit 27 **WBO:** CRC Write Byte Order Selection bit[1]
1 = Source data is written to the destination re-ordered as defined by BYTO<1:0>
0 = Source data is written to the destination unaltered

bit 26-25 **Unimplemented:** Read as ‘0’

bit 24 **BITO:** CRC Bit Order Selection bit
When CRCTYP (DCRCCON<15>) = 1 (CRC module is in IP Header mode):
1 = The IP header checksum is calculated Least Significant bit (LSb) first (i.e., reflected)
0 = The IP header checksum is calculated Most Significant bit (MSb) first (i.e., not reflected)

When CRCTYP (DCRCCON<15>) = 0 (CRC module is in LFSR mode):
1 = The LFSR CRC is calculated Least Significant bit first (i.e., reflected)
0 = The LFSR CRC is calculated Most Significant bit first (i.e., not reflected)

bit 23-13 **Unimplemented:** Read as ‘0’

bit 12-8 **PLEN<4:0>:** Polynomial Length bits
When CRCTYP (DCRCCON<15>) = 1 (CRC module is in IP Header mode):
These bits are unused.

When CRCTYP (DCRCCON<15>) = 0 (CRC module is in LFSR mode):
Denotes the length of the polynomial – 1.

bit 7 **CRCEN:** CRC Enable bit
1 = CRC module is enabled and channel transfers are routed through the CRC module
0 = CRC module is disabled and channel transfers proceed normally

Note 1: When WBO = 1, unaligned transfers are not supported and the CRCAPP bit cannot be set.

REGISTER 9-9: DCHxINT: DMA CHANNEL ‘x’ INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as ‘0’

bit 23 **CHSDIE:** Channel Source Done Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 22 **CHSHIE:** Channel Source Half Empty Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 21 **CHDDIE:** Channel Destination Done Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 20 **CHDHIE:** Channel Destination Half Full Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 19 **CHBCIE:** Channel Block Transfer Complete Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 18 **CHCCIE:** Channel Cell Transfer Complete Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 17 **CHTAIE:** Channel Transfer Abort Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 16 **CHERIE:** Channel Address Error Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7 **CHSDIF:** Channel Source Done Interrupt Flag bit
1 = Channel Source Pointer has reached end of source (CHSPTR = CHSSIZ)
0 = No interrupt is pending

bit 6 **CHSHIF:** Channel Source Half Empty Interrupt Flag bit
1 = Channel Source Pointer has reached midpoint of source (CHSPTR = CHSSIZ/2)
0 = No interrupt is pending

bit 5 **CHDDIF:** Channel Destination Done Interrupt Flag bit
1 = Channel Destination Pointer has reached end of destination (CHDPTR = CHDSIZ)
0 = No interrupt is pending

TABLE 11-1: INPUT PIN SELECTION

Peripheral Pin	[*pin name*]R SFR	[*pin name*]R bits	[*pin name*]R Value to RPn Pin Selection
INT4	INT4R	INT4R<3:0>	`0000` = RPA0 `0001` = RPB3 `0010` = RPB4 `0011` = RPB15 `0100` = RPB7 `0101` = RPC7(2) `0110` = RPC0(1) `0111` = RPC5(2) `1000` = Reserved • • • `1111` = Reserved
T2CK	T2CKR	T2CKR<3:0>	
IC4	IC4R	IC4R<3:0>	
$\overline{\text{SS1}}$	SS1R	SS1R<3:0>	
REFCLKI	REFCLKIR	REFCLKIR<3:0>	
INT3	INT3R	INT3R<3:0>	`0000` = RPA1 `0001` = RPB5 `0010` = RPB1 `0011` = RPB11 `0100` = RPB8 `0101` = RPA8(2) `0110` = RPC8(2) `0111` = RPA9(2) `1000` = Reserved • • • `1111` = Reserved
T3CK	T3CKR	T3CKR<3:0>	
IC3	IC3R	IC3R<3:0>	
$\overline{\text{U1CTS}}$	U1CTSR	U1CTSR<3:0>	
U2RX	U2RXR	U2RXR<3:0>	
SDI1	SDI1R	SDI1R<3:0>	
INT2	INT2R	INT2R<3:0>	`0000` = RPA2 `0001` = RPB6 `0010` = RPA4 `0011` = RPB13 `0100` = RPB2 `0101` = RPC6(2) `0110` = RPC1(1) `0111` = RPC3(1) `1000` = Reserved • • • `1111` = Reserved
T4CK	T4CKR	T4CKR<3:0>	
IC1	IC1R	IC1R<3:0>	
IC5	IC5R	IC5R<3:0>	
U1RX	U1RXR	U1RXR<3:0>	
$\overline{\text{U2CTS}}$	U2CTSR	U2CTSR<3:0>	
SDI2	SDI2R	SDI2R<3:0>	
OCFB	OCFBR	OCFBR<3:0>	
INT1	INT1R	INT1R<3:0>	`0000` = RPA3 `0001` = RPB14 `0010` = RPB0 `0011` = RPB10 `0100` = RPB9 `0101` = RPC9(1) `0110` = RPC2(2) `0111` = RPC4(2) `1000` = Reserved • • • `1111` = Reserved
T5CK	T5CKR	T5CKR<3:0>	
IC2	IC2R	IC2R<3:0>	
$\overline{\text{SS2}}$	SS2R	SS2R<3:0>	
OCFA	OCFAR	OCFAR<3:0>	

Note 1: This pin is not available on 28-pin devices.
2: This pin is only available on 44-pin devices.

REGISTER 18-1: I2CxCON: I^{2}C CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
	ON(1)	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN
7:0	R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN

Legend:	HC = Cleared in Hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15 **ON:** I^{2}C Enable bit(1)

`1` = Enables the I^{2}C module and configures the SDA and SCL pins as serial port pins
`0` = Disables the I^{2}C module; all I^{2}C pins are controlled by PORT functions

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **SIDL:** Stop in Idle Mode bit

`1` = Discontinue module operation when the device enters Idle mode
`0` = Continue module operation when the device enters Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I^{2}C slave)

`1` = Release SCLx clock
`0` = Hold SCLx clock low (clock stretch)

If STREN = `1`:
Bit is R/W (i.e., software can write ‘`0`’ to initiate stretch and write ‘`1`’ to release clock). Hardware clear at beginning of slave transmission. Hardware clear at end of slave reception.

If STREN = `0`:
Bit is R/S (i.e., software can only write ‘`1`’ to release clock). Hardware clear at beginning of slave transmission.

bit 11 **STRICT:** Strict I^{2}C Reserved Address Rule Enable bit

`1` = Strict reserved addressing is enforced. Device does not respond to reserved address space or generate addresses in reserved address space.
`0` = Strict I^{2}C Reserved Address Rule not enabled

bit 10 **A10M:** 10-bit Slave Address bit

`1` = I2CxADD is a 10-bit slave address
`0` = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit

`1` = Slew rate control disabled
`0` = Slew rate control enabled

bit 8 **SMEN:** SMBus Input Levels bit

`1` = Enable I/O pin thresholds compliant with SMBus specification
`0` = Disable SMBus input thresholds

Note 1: When using 1:1 PBCLK divisor, the user’s software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.

REGISTER 20-5: PMSTAT: PARALLEL PORT STATUS REGISTER (SLAVE MODES ONLY)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R/W-0, HSC	U-0	U-0	R-0	R-0	R-0	R-0
	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F
7:0	R-1	R/W-0, HSC	U-0	U-0	R-1	R-1	R-1	R-1
	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E

Legend:	HSC = Set by Hardware; Cleared by Software		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15 **IBF:** Input Buffer Full Status bit

1 = All writable input buffer registers are full
0 = Some or all of the writable input buffer registers are empty

bit 14 **IBOV:** Input Buffer Overflow Status bit

1 = A write attempt to a full input byte buffer occurred (must be cleared in software)
0 = No overflow occurred

bit 13-12 **Unimplemented:** Read as ‘0’

bit 11-8 **IBxF:** Input Buffer ‘x’ Status Full bits

1 = Input Buffer contains data that has not been read (reading buffer will clear this bit)
0 = Input Buffer does not contain any unread data

bit 7 **OBE:** Output Buffer Empty Status bit

1 = All readable output buffer registers are empty
0 = Some or all of the readable output buffer registers are full

bit 6 **OBUF:** Output Buffer Underflow Status bit

1 = A read occurred from an empty output byte buffer (must be cleared in software)
0 = No underflow occurred

bit 5-4 **Unimplemented:** Read as ‘0’

bit 3-0 **OBxE:** Output Buffer ‘x’ Status Empty bits

1 = Output buffer is empty (writing data to the buffer will clear this bit)
0 = Output buffer contains data that has not been transmitted

REGISTER 22-5: AD1CSSL: ADC INPUT SCAN SELECT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CSSL15	CSSL14	CSSL13	CSSL12	CSSL11	CSSL10	CSSL9	CSSL8
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CSSL7	CSSL6	CSSL5	CSSL4	CSSL3	CSSL2	CSSL1	CSSL0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CSSL<15:0>:** ADC Input Pin Scan Selection bits(1,2)

`1` = Select ANx for input scan
`0` = Skip ANx for input scan

Note 1: CSSL = ANx, where ‘x’ = 0-12; CSSL13 selects CTMU input for scan; CSSL14 selects IVREF for scan; CSSL15 selects VSS for scan.

2: On devices with less than 13 analog inputs, all CSSLx bits can be selected; however, inputs selected for scan without a corresponding input on the device will convert to VREFL.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge1 Status bit

Indicates the status of Edge1 and can be written to control edge source

1 = Edge1 has occurred
0 = Edge1 has not occurred

bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit

1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit

1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits

1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as ‘0’

bit 15 **ON:** ON Enable bit

1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUSIDL:** Stop in Idle Mode bit

1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **TGEN:** Time Generation Enable bit(1)

1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit

1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘1110’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘1’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 “Electrical Characteristics”** for current values.

4: This bit setting is not available for the CTMU temperature diode.

26.0 POWER-SAVING FEATURES

> **Note:** This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. "Power-Saving Features"** (DS60001130), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This section describes power-saving features for the PIC32MX1XX/2XX 28/36/44-pin Family. The PIC32 devices offer a total of nine methods and modes, organized into two categories, that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

26.1 Power Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK and by individually disabling modules. These methods are grouped into the following categories:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers
- LPRC Run mode: the CPU is clocked from the LPRC clock source
- SOSC Run mode: the CPU is clocked from the SOSC clock source

In addition, the Peripheral Bus Scaling mode is available where peripherals are clocked at the programmable fraction of the CPU clock (SYSCLK).

26.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which Halt the clock to the CPU. These modes operate with all clock sources, as follows:

- POSC Idle mode: the system clock is derived from the POSC. The system clock source continues to operate. Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- SOSC Idle mode: the system clock is derived from the SOSC. Peripherals continue to operate, but can optionally be individually disabled.
- LPRC Idle mode: the system clock is derived from the LPRC. Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.
- Sleep mode: the CPU, the system clock source and any peripherals that operate from the system clock source are Halted. Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

26.3 Power-Saving Operation

Peripherals and the CPU can be Halted or disabled to further reduce power consumption.

26.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device power-saving operating modes. The CPU and most peripherals are Halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep.

Sleep mode includes the following characteristics:

- The CPU is halted
- The system clock source is typically shutdown. See **Section 26.3.3 "Peripheral Bus Scaling Method"** for specific information.
- There can be a wake-up delay based on the oscillator selection
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode
- The BOR circuit remains operative during Sleep mode
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode
- Some peripherals can continue to operate at limited functionality in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator (e.g., RTCC, Timer1 and Input Capture).
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep
- The USB module can override the disabling of the Posc or FRC. Refer to the USB section for specific details.
- Modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption

REGISTER 27-6: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0>(1)				DEVID<27:24>(1)			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16>(1)							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8>(1)							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0>(1)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-28 **VER<3:0>:** Revision Identifier bits(1)

bit 27-0 **DEVID<27:0>:** Device ID bits(1)

Note 1: See the *“PIC32 Flash Programming Specification”* (DS60001145) for a list of Revision and Device ID values.

TABLE 30-18: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
OS50	F_{PLLI}	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	3.92	—	5	MHz	ECPLL, HSPLL, XTPLL, FRCPLL modes
OS51	F_{SYS}	On-Chip VCO System Frequency	60	—	120	MHz	—
OS52	T_{LOCK}	PLL Start-up Time (Lock Time)	—	—	2	ms	—
OS53	D_{CLK}	CLKO Stability[2] (Period Jitter or Cumulative)	-0.25	—	+0.25	%	Measured over 100 ms period

Note 1: These parameters are characterized, but not tested in manufacturing.

2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 40 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{40}{20}}} = \frac{D_{CLK}}{1.41}$$

TABLE 30-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Internal FRC Accuracy @ 8.00 MHz[1]						
F20b	FRC	-0.9	—	+0.9	%	—

Note 1: Frequency calibrated at 25°C and 3.3V. The TUN bits can be used to compensate for temperature drift.

TABLE 30-20: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
LPRC @ 31.25 kHz[1]						
F21	LPRC	-15	—	+15	%	—

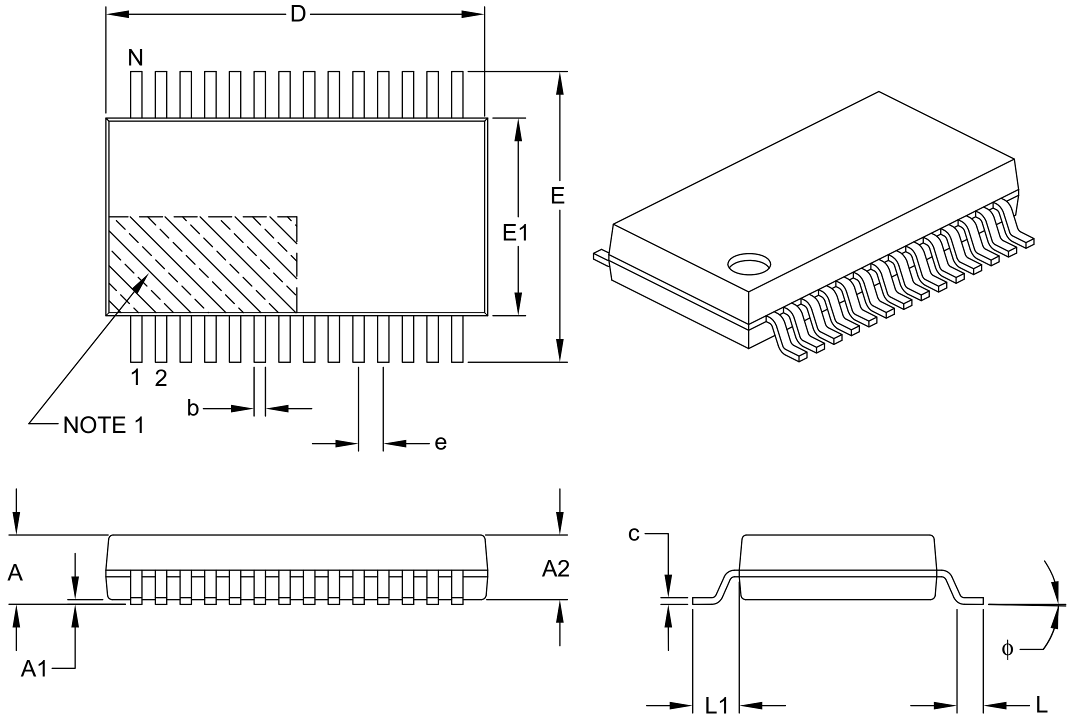
Note 1: Change of LPRC frequency as V_{DD} changes.

33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

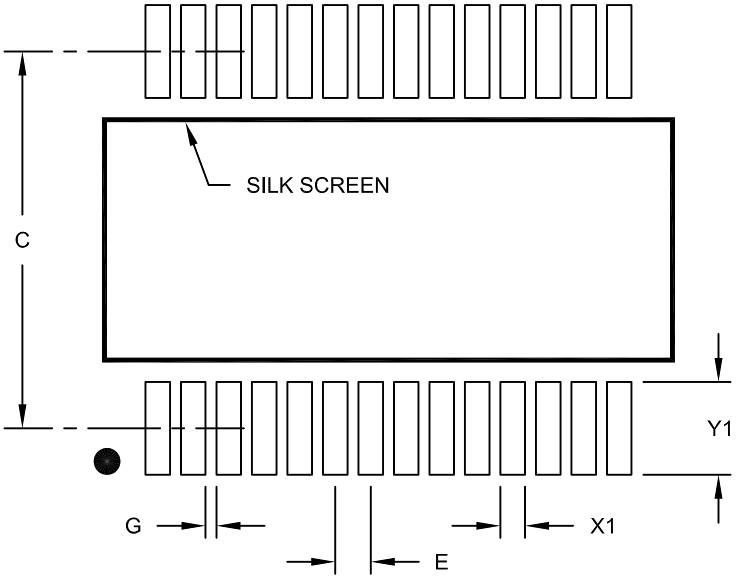
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

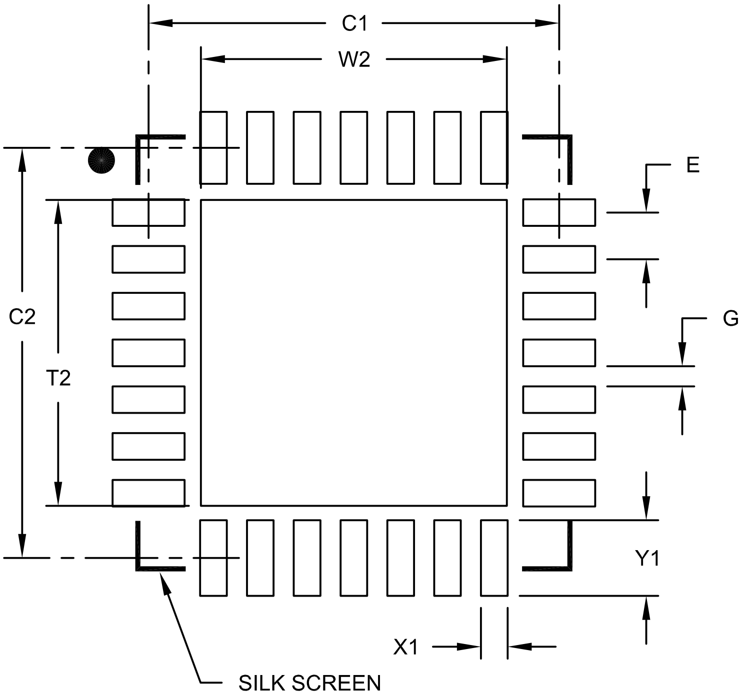
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

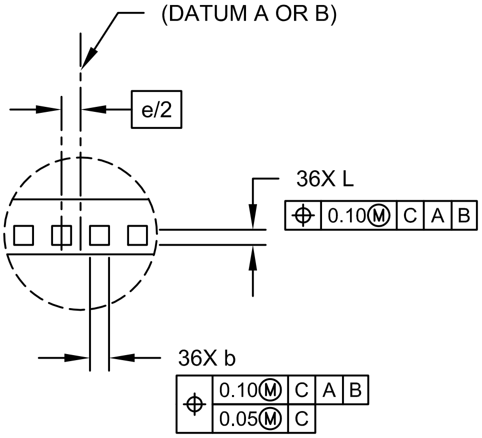
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

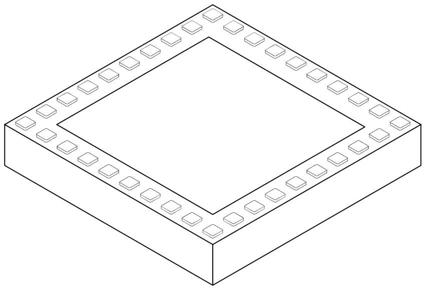
Microchip Technology Drawing No. C04-2105A

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

Revision E (October 2012)

All singular pin diagram occurrences of CVREF were changed to: CVREFOUT. In addition, minor text and formatting changes were incorporated throughout the document.

All major changes are referenced by their respective section in Table A-4.

TABLE A-4: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog"	Updated the following feature sections: • **"Operating Conditions"** • **"Communication Interfaces"**
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Removed Section 2.8 "Configuration of Analog and Digital Pins During ICSP Operations".
3.0 "CPU"	Removed references to GPR shadow registers in **3.1 "Features"** and **3.2.1 "Execution Unit"**.
4.0 "Memory Organization"	Updated the BRG bit range in the SPI1 and SPI2 Register Map (see Table 4-8). Added the PWP<6> bit to the Device Configuration Word Summary (see Table 4-17).
5.0 "Flash Program Memory"	Added a note with Flash page size and row size information.
7.0 "Interrupt Controller"	Updated the TPC<2:0> bit definitions (see Register 7-1). Updated the IPTMR<31:0> bit definition (see Register 7-3).
8.0 "Oscillator Configuration"	Updated the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Updated the RODIV<14:0> bit definitions (see Register 8-3).
10.0 "USB On-The-Go (OTG)"	Updated the Notes in the USB Interface Diagram (see Figure 10-1).
18.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the baud rate range in the list of primary features.
26.0 "Special Features"	Added the PWP<6> bit to the Device Configuration Word 0 (see Register 26-1).
29.0 "Electrical Characteristics"	Added Note 1 to Operating MIPS vs. Voltage (see Table 29-1). Added Note 2 to DC Temperature and Voltage Specifications (see Table 29-4). Updated the Conditions for parameter DC25 in DC Characteristics: Operating Current (IDD) (see Table 29-5). Added Note 2 to Electrical Characteristics: BOR (see Table 29-10). Added Note 4 to Comparator Specifications (see Table 29-12). Added Note 5 to ADC Module Specifications (see Table 29-32). Updated the 10-bit Conversion Rate Parameters and added Note 3 (see Table 29-33). Added Note 4 to the Analog-to-Digital Conversion Timing Requirements (see Table 29-34). Added Note 3 to CTMU Current Source Specifications (see Table 29-39).
30.0 "50 MHz Electrical Characteristics"	New chapter with electrical characteristics for 50 MHz devices.
31.0 "Packaging Information"	The 36-pin and 44-pin VTLA packages have been updated.